

REVISIONS																			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED																
A	Removed vendor CAGE 61772 from device types 01YX and 02YX. Technical change was made in table I. Editorial changes throughout.	1990 JUL 24	<i>W. Heckman</i>																

REV	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
SHEET																				
REV																				
SHEET																				

REV STATUS OF SHEETS	REV SHEET	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19

PMIC N/A STANDARDIZED MILITARY DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A	PREPARED BY <i>Tim Noh</i> CHECKED BY <i>Tim Noh</i> APPROVED BY <i>William K. Heckman</i> DRAWING APPROVAL DATE 1 AUGUST 1988 REVISION LEVEL A	DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444 MICROCIRCUITS, DIGITAL, CMOS 16-BIT MICROPROGRAM SEQUENCER, MONOLITHIC SILICON SIZE A CAGE CODE 67268 SHEET <div style="text-align: right; font-size: 1.5em;">1</div>
--	--	--

DESC FORM 193
SEP 87

• U.S. GOVERNMENT PRINTING OFFICE: 1987 — 748-129/60911

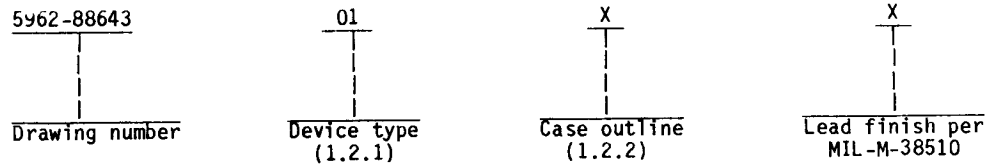
DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E1773-3

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device types shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	49C410	16-bit CMOS microprogram sequencer with 33 deep stack
02	49C410A	16-bit CMOS microprogram sequencer with 33 deep stack

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
X	D-14, (48-lead, 2.435" x .620" x .225"), dual-in-line package
Y	See figure 1, (48-terminal, .565" x .565" x .120"), square chip carrier package

1.3 Absolute maximum ratings. 1/

Supply voltage (V_{CC})	-0.5 V dc to +7.0 V dc
DC output current	+30 mA
Power dissipation (P_D) 2/-	1.0 W
Storage temperature	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	300°
Junction temperature (T_J)	+175°C
Thermal resistance, junction-to-case (θ_{JC}):	
Case X	See MIL-M-38510, appendix C
Case Y	20°C/W

1.4 Recommended operating conditions.

Supply voltage (V_{CC})	+4.5 V dc to +5.5 V dc
Case operating temperature (T_C)	-55°C to +125°C
Minimum logic high voltage (V_{IH})	2.0 V dc
Maximum logic low voltage (V_{IL})	0.8 V dc

1/ ATT voltage referenced to GND

2/ Must withstand the added P_D due to short circuit test, e.g., I_{OS} .

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-88643	
		REVISION LEVEL	SHEET 2

2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 2 herein.

3.2.2 Instruction set. The instruction set shall be as specified on figure 3 herein.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 4 herein.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 3

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T _C < +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified		Group A subgroups	Device type	Limits		Unit
						Min	Max	
High level output	V _{OH}	V _{CC} = 4.5 V V _{IL} = 0.8 V V _{IH} = 2.0 V	I _{OH} = -300 μA	1,2,3	A11	4.3		V
			I _{OH} = -12 mA			2.4		
Low level output	V _{OL}	V _{CC} = 4.5 V V _{IL} = 0.8 V V _{IH} = 2.0 V	I _{OL} = 300 μA	1,2,3	A11		0.2	V
			I _{OL} = 20 mA				0.5	
High level input current	I _{IH}	V _{CC} = 5.5 V, V _{IN} = 5.5 V		1,2,3	A11		5.0	μA
Low level input current	I _{IL}	V _{CC} = 5.5 V, V _{IN} = GND		1,2,3	A11		-5.0	μA
Short circuit output current	I _{OS}	V _{CC} = 4.5 V, V _{OUT} = GND <u>1/</u>		1,2,3	A11	-30		mA
Off state high impedance output current	I _{OZ}	V _{CC} = 5.5 V	V _{OUT} = 0 V	1,2,3	A11		-10	μA
			V _{OUT} = 5.5 V				10	
Quiescent power supply current (CMOS inputs)	I _{CCQH}	V _{CC} = 5.5 V, V _{IL} ≤ 0.2 V, V _{IH} ≥ 5.3 V, f _{CP} = 0, CP = H		1,2,3	A11		50	mA
Quiescent power supply current (CMOS inputs)	I _{CCQL}	V _{CC} = 5.5 V, V _{IL} ≤ 0.2 V, V _{IH} ≥ 5.3 V, f _{CP} = 0, CP = L		1,2,3	A11		50	
Quiescent power supply current (TTL inputs) <u>2/</u>	I _{CCT}	V _{CC} = 5.5 V, V _{IN} = 3.4 V, f _{CP} = 0		1,2,3	A11		0.5	mA/ input

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL	SHEET 4

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Dynamic power supply current	I _{CCD}	V _{CC} = 5.5 V, V _{IL} ≤ 0.2 V, V _{IH} = 5.3 V, outputs open, OE = L	1,2,3	A11		3.0	mA/MHz
Total power supply current <u>3/</u>	I _{CC}	V _{CC} = 5.5 V, f _{CP} = 10 MHz, outputs open, V _{IH} > 5.3 V, V _{IL} < 0.2 V, OE = L, CP = 50% duty cycle	1,2,3	A11		80	mA
		V _{CC} = 5.5 V, f _{CP} = 10 MHz, outputs open, V _{IH} = 3.4 V, V _{IL} = 0.4 V, OE = L, CP = 50% duty cycle				90	
Input capacitance	C _{IN}	See 4.3.1c	4	A11		12	pF
Output capacitance	C _{OUT}	See 4.3.1c	4	A11		15	pF
Functional test		See 4.3.1d	7, 8	A11			
Setup time D ₁ to R	t _{S1}	See figure 5 <u>4/</u>	9,10,11	01	16		ns
				02	7.0		ns
Setup time D ₁ to PC	t _{S2}	See figure 5 <u>4/</u>	9,10,11	01	30		ns
				02	15		ns
Setup time I _{O-3}	t _{S3}	See figure 5 <u>4/</u>	9,10,11	01	38		ns
				02	25		ns

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 5

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
Setup time CC	t _{S4}	See figure 5 4/	9,10,11	01	35		ns	
				02	18		ns	
Setup time CCEN	t _{S5}		9,10,11	01	35		ns	
				02	18		ns	
Setup time CI	t _{S6}		9,10,11	01	18		ns	
				02	7.0		ns	
Setup time RLD	t _{S7}		9,10,11	01	20		ns	
				02	12		ns	
Hold time D ₁ to R	t _{H1}		9,10,11	01	0		ns	
				02	0		ns	
Hold time D ₁ to PC	t _{H2}		9,10,11	01	0		ns	
				02	0		ns	

See footnotes at end of table.

**STANDARDIZED
MILITARY DRAWING**

 DEFENSE ELECTRONICS SUPPLY CENTER
 DAYTON, OHIO 45444

 SIZE
A

5962-88643

REVISION LEVEL

SHEET

6

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Hold time I _{O-3}	t _{H3}	See figure 5 4/	9,10,11	01	0		ns
				02	0		ns
	9,10,11		01	0		ns	
			02	0		ns	
Hold time CC	t _{H4}		9,10,11	01	0		ns
				02	0		ns
Hold time CCEN	t _{H5}		9,10,11	01	0		ns
				02	0		ns
Hold time CI	t _{H6}		9,10,11	01	0		ns
				02	0		ns
Hold time RLD	t _{H7}		9,10,11	01	0		ns
				02	0		ns
Propagation delay D ₀₋₁₁ to Y	t _{PD1}	9,10,11	01		25	ns	
			02		15	ns	

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL	SHEET 7

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Propagation delay I _{O-3} to Y	tpD2	See figure 5 <u>4/</u>	9,10,11	01		40	ns
				02		25	ns
Propagation delay CC to Y	tpD3		9,10,11	01		36	ns
				02		20	ns
Propagation delay CCEN to Y	tpD4		9,10,11	01		36	ns
				02		20	ns
Propagation delay CP to Y	tpD5		9,10,11	01		46	ns
				02		33	ns
Propagation delay OE to Y (enable)	tpD6		9,10,11	01		25	ns
				02		13	ns
Propagation delay OE to Y (disable) <u>5/</u>	tpD7		9,10,11	01		30	ns
				02		13	ns

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL	SHEET 8

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C V _{CC} = 5.0 V dc ±10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Propagation delay I _{O-3} to PL, VECT, MAP	tpD8	See figure 5 4/	9,10,11	01		35	ns
				02		15	ns
Propagation delay CP to FULL	tpD9		9,10,11	01		35	ns
				02		25	ns
Clock LOW time	tpW1		9,10,11	01	25		ns
				02	20		ns
Clock HIGH time	tpW2		9,10,11	01	25		ns
				02	20		ns
Clock period	tp		9,10,11	01	51		ns
				02	40		ns

1/ Not more than one output should be shorted at one time. Duration of the short circuit test should not exceed one second.

2/ I_{CCT} is derived by measuring the total current with all the inputs tied together at 3.4 V, subtracting out I_{CCQH}, then dividing by the total number of inputs.

3/ $I_{CC} = I_{CCQH} (CD_H) + I_{CCQL} (1 - CD_H) + I_{CCT} (N_T \times D_H) + I_{CCD} (f_{CP})$.

Where: CD_H = Clock duty cycle high period.

D_H = Data duty cycle TTL high period (V_{IN} = 3.4 V).

N_T = Number of dynamic inputs driven at TTL levels.

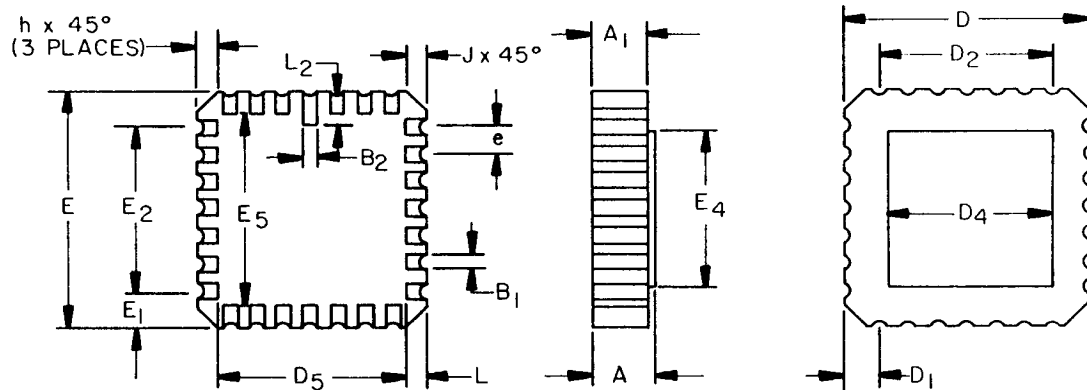
f_{CP} = Clock input frequency.

4/ Unless otherwise specified, the input pulse level shall be between 0 V to 3.0 V, input rise/fall times shall be 1.0 V/ns and input and output timing reference levels shall be 1.5 V.

5/ Disable time is measured to 0.5 V change on output voltage level with C_L = 5 pF.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL	SHEET 9

Case Y



Inches	mm	Inches	mm
.012	0.30	.077	1.96
.017	0.43	.090	2.29
.020	0.51	.093	2.36
.023	0.58	.120	3.05
.033	0.84	.440	11.18
.040	1.02	.480	12.19
.045	1.14	.546	13.87
.047	1.19	.554	14.07
.055	1.40	.572	14.53
.060	1.52		

FIGURE 1. Case outline.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 10

Number of leads (N)	48		Number of leads (N)	48	
	Min	Max		Min	Max
A	.055	.120	E ₁	.060 REF	
A ₁	.045	.090	E ₂	.440 BSC	
B ₁	.017	.023	E ₄		.546
B ₂	.017	.033	E ₅	.480 REF	
D	.554	.572	e	.040 BSC	
D ₁	.060 REF		h	.012 Radius	
D ₂	.440 BSC		J	.020 REF	
D ₄		.546	L	.033	.047
D ₅	.480 REF		L ₂	.077	.093
E	.554	.572	N	48	
			ND	12	

ND = NE - Number of leads per side.

FIGURE 1. Case outline - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 11

Cases X and Y

Pin number	Terminal connection	Pin number	Terminal connection
1	Y ₁₃	25	D ₁₅
2	D ₁₃	26	Y ₁₅
3	Y ₄	27	D ₈
4	D ₄	28	Y ₈
5	Y ₅	29	D ₉
6	D ₅	30	Y ₉
7	$\overline{\text{VECT}}$	31	D ₁₀
8	$\overline{\text{PL}}$	32	Y ₁₀
9	$\overline{\text{MAP}}$	33	D ₁₁
10	I ₃	34	Y ₁₁
11	I ₂	35	$\overline{\text{OE}}$
12	V _{3CC}	36	GND
13	I ₁	37	CP
14	I ₀	38	CI
15	$\overline{\text{CCEN}}$	39	Y ₀
16	$\overline{\text{CC}}$	40	D ₀
17	$\overline{\text{RLD}}$	41	Y ₁
18	$\overline{\text{FULL}}$	42	D ₁
19	D ₆	43	Y ₂
20	Y ₆	44	D ₂
21	D ₇	45	Y ₃
22	Y ₇	46	D ₃
23	D ₁₄	47	Y ₁₂
24	Y ₁₄	48	D ₁₂

FIGURE 2. Terminal connections.

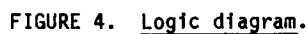
STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 12

I3-I0	Mnemonic	CC	Counter test	Stack	Address source	Register/counter	Enable/select
0	JZ	X	X	Clear	0	NC	PL
1	CJS	Pass Fail	X X	Push NC	D Pc	NC NC	PL PL
2	JMAP	X	X	NC	D	NC	MAP
3	CJP	Pass Fail	X X	NC NC	D Pc	NC NC	PL PL
4	PUSH	Pass Fail	X X	Push Push	Pc Pc	Load NC	PL PL
5	JSRP	Pass Fail	X X	Push Push	D R	NC NC	PL PL
6	CJV	Pass Fail	X X	NC NC	D Pc	NC NC	VECT VECT
7	JRP	Pass Fail	X X	NC NC	D R	NC NC	PL PL
8	RFCT	X X	= 0 Not = 0	Pop NC	Pc Stack	NC DEC	PL PL
9	RPCT	X X	= 0 Not = 0	NC NC	Pc D	NC DEC	PL PL
10	RPCT	Pass Fail	X X	Pop NC	Stack Pc	NC NC	PL PL
11	CJPP	Pass Fail	X X	Pop NC	D Pc	NC NC	PL PL
12	LDCT	X	X	NC	Pc	Load	PL
13	LOOP	Pass Fail	X X	Pop NC	Pc Stack	NC NC	PL PL
14	CONT	X	X	NC	Pc	NC	PL
15	TWB	Pass Pass Fail Fail	= 0 Not = 0 = 0 Not = 0	Pop Pop Pop NC	Pc Pc D Stack	NC DEC NC DEC	PL PL PL PL

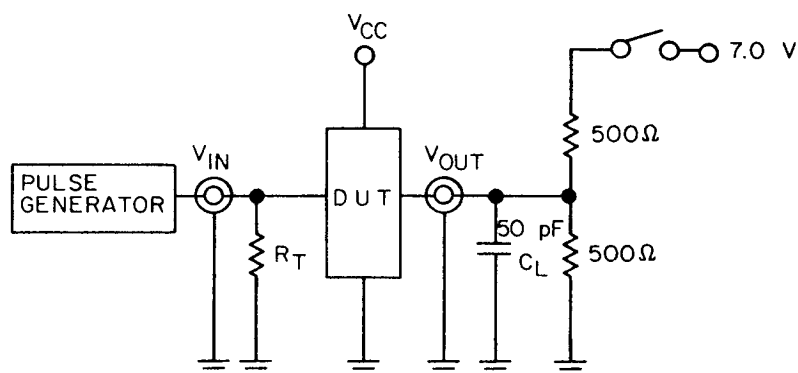
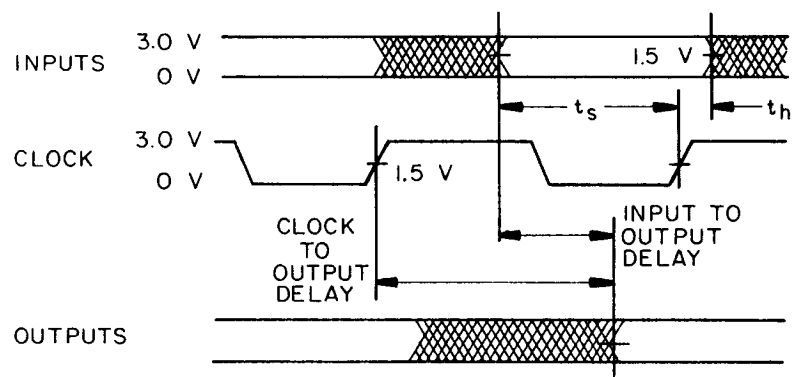
NC = No change; DEC = Decrement

FIGURE 3. Instruction set.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-88643	
		REVISION LEVEL A	SHEET 13



14



Test	Switch
Open drain Disable low Enable low	Closed
All other outputs	Open

C_L = Load capacitance: Includes jig and probe capacitance
 R_T = Termination resistance: should be equal to Z_{OUT} of the pulse generator

FIGURE 5. Switching waveforms and test circuit.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL	SHEET 15

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DESC-ECC shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition D using the circuit submitted with the certificate of compliance (see 3.6 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 4 (C_{IN} and C_{OUT} measurement) shall be measured only initially test and after process or design changes which may affect capacitance.

d. Subgroups 7 and 8 functional testing shall include the verification of instruction set.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 16

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1*, 2, 3, 4, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3, 7, 8

* PDA applies to subgroup 1.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 17

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using Dd Form 1693, Engineering Change Proposal (Short Form).

6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECC telephone (513) 296-6022.

6.5 Comments. Comments on this drawing should be directed to DESC-ECC, Dayton, Ohio 45444, or telephone (513) 296-8525.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. Additional sources will be added as they become available. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to DESC-ECC. The approved sources of supply listed below are for information purposes only and are current only to the date of the last action of this document.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1/</u>
5962-8864301XX	61772	IDT49C41OCB
5962-8864301YX	<u>2/</u>	IDT49C41OLB
5962-8864302XX	61772	IDT49C41OACB
5962-8864302YX	<u>2/</u>	IDT49C41OALB

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

2/ Approved source of supply not available.

Vendor CAGE
number

61772

Vendor name
and address

Integrated Device Technology Incorporated
1566 Moffett Boulevard
Salinas CA 93905
Point of contact: 3236 Scott Boulevard
Santa Clara CA 95054

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-88643
		REVISION LEVEL A	SHEET 18

DESC FORM 193A
SEP 87

☆ U. S. GOVERNMENT PRINTING OFFICE: 1989-749-033

019872

JAN 07 1991